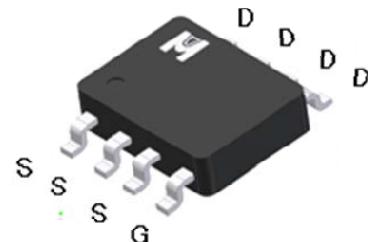
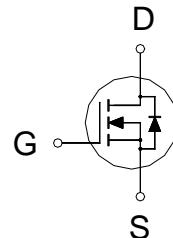


N-Channel Logic Level Enhancement Mode Field Effect Transistor

Product Summary:

BV <sub>DSS</sub>	40V
R <sub>DSON</sub> (MAX.)	22mΩ
I <sub>D</sub>	9A



Pb-Free Lead Plating & Halogen Free



**ABSOLUTE MAXIMUM RATINGS (T<sub>A</sub> = 25 °C Unless Otherwise Noted)**

PARAMETERS/TEST CONDITIONS		SYMBOL	LIMITS	UNIT
Gate-Source Voltage		V <sub>GS</sub>	±20	V
Continuous Drain Current	T <sub>A</sub> = 25 °C	I <sub>D</sub>	9	A
	T <sub>A</sub> = 70 °C		8	
Pulsed Drain Current <sup>1</sup>		I <sub>DM</sub>	36	
Power Dissipation	T <sub>A</sub> = 25 °C	P <sub>D</sub>	2.5	W
	T <sub>A</sub> = 70 °C		1.6	
Operating Junction & Storage Temperature Range		T <sub>j</sub> , T <sub>stg</sub>	-55 to 150	°C

**THERMAL RESISTANCE RATINGS**

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNIT
Junction-to-Case	R <sub>θJC</sub>	25	50	°C / W
Junction-to-Ambient <sup>3</sup>	R <sub>θJA</sub>			

<sup>1</sup>Pulse width limited by maximum junction temperature.

<sup>2</sup>Duty cycle ≤ 1%

<sup>3</sup>50°C / W when mounted on a 1 in<sup>2</sup> pad of 2 oz copper.

ELECTRICAL CHARACTERISTICS ( $T_A = 25^\circ\text{C}$ , Unless Otherwise Noted)

PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNIT
			MIN	TYP	MAX	
STATIC						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0V, I_D = 250\mu\text{A}$	40			V
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = 250\mu\text{A}$	1.0	1.7	3.0	
Gate-Body Leakage	$I_{\text{GSS}}$	$V_{\text{DS}} = 0V, V_{\text{GS}} = \pm 20V$			$\pm 100$	nA
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{DS}} = 32V, V_{\text{GS}} = 0V$			1	$\mu\text{A}$
		$V_{\text{DS}} = 30V, V_{\text{GS}} = 0V, T_J = 125^\circ\text{C}$			25	
On-State Drain Current <sup>1</sup>	$I_{\text{D}(\text{ON})}$	$V_{\text{DS}} = 5V, V_{\text{GS}} = 10V$	9			A
Drain-Source On-State Resistance <sup>1</sup>	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}} = 10V, I_D = 9A$		20	22	$\text{m}\Omega$
		$V_{\text{GS}} = 4.5V, I_D = 5A$		30	37	
Forward Transconductance <sup>1</sup>	$g_{\text{fs}}$	$V_{\text{DS}} = 5V, I_D = 9A$		20		S
DYNAMIC						
Input Capacitance	$C_{\text{iss}}$	$V_{\text{GS}} = 0V, V_{\text{DS}} = 20V, f = 1\text{MHz}$		536		pF
Output Capacitance	$C_{\text{oss}}$			83		
Reverse Transfer Capacitance	$C_{\text{rss}}$			66		
Total Gate Charge <sup>1,2</sup>	$Q_g$	$V_{\text{DS}} = 20V, V_{\text{GS}} = 10V,$ $I_D = 9A$		14.5		nC
Gate-Source Charge <sup>1,2</sup>	$Q_{\text{gs}}$			2.1		
Gate-Drain Charge <sup>1,2</sup>	$Q_{\text{gd}}$			4.3		
Turn-On Delay Time <sup>1,2</sup>	$t_{\text{d}(\text{on})}$	$V_{\text{DS}} = 20V,$ $I_D = 1A, V_{\text{GS}} = 10V, R_{\text{GS}} = 6\Omega$		5		nS
Rise Time <sup>1,2</sup>	$t_r$			10		
Turn-Off Delay Time <sup>1,2</sup>	$t_{\text{d}(\text{off})}$			15		
Fall Time <sup>1,2</sup>	$t_f$			12		
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS ( $T_C = 25^\circ\text{C}$ )						
Continuous Current	$I_S$				2.3	A
Pulsed Current <sup>3</sup>	$I_{\text{SM}}$				9.2	
Forward Voltage <sup>1</sup>	$V_{\text{SD}}$	$I_F = I_S, V_{\text{GS}} = 0V$			1.3	V

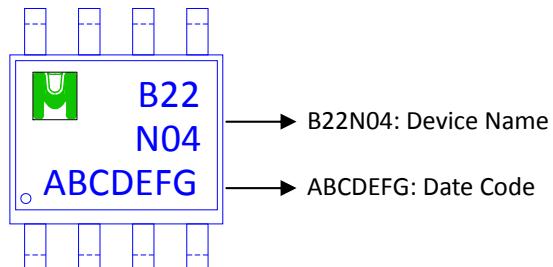
<sup>1</sup>Pulse test : Pulse Width  $\leq 300 \mu\text{sec}$ , Duty Cycle  $\leq 2\%$ .

<sup>2</sup>Independent of operating temperature.

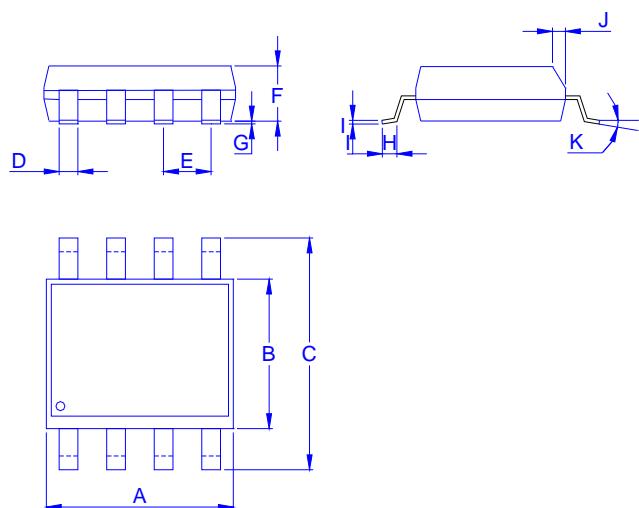
<sup>3</sup>Pulse width limited by maximum junction temperature.

Ordering & Marking Information:

Device Name: EMB22N04G for SOP-8



Outline Drawing



Dimension in mm

Dimension	A	B	C	D	E	F	G	H	I	J	K
Min.	4.70	3.70	5.80	0.33		1.20	0.08	0.40	0.19	0.25	0°
Typ.					1.27						
Max.	5.10	4.10	6.20	0.51		1.62	0.28	0.83	0.26	0.50	8°

TYPICAL CHARACTERISTICS

